

ABSTRACT OF THE DISCLOSURE

The present invention generally provides a fluid delivery system with particular application to electroplating. Two or more reservoirs are fluidly connected to one or more processing chambers by fluid delivery lines. A gas source is coupled to the
5 reservoirs to selectively pressurize the reservoirs and cause fluid flow therefrom to the processing chambers through the fluid delivery lines. The fluid levels in the reservoirs and the processing chambers are controlled to facilitate gravity-assisted flow of fluid from the processing chambers to the reservoirs via the fluid delivery line when the fluid
10 levels in the processing chambers are higher than the fluid levels in the reservoirs. In operation, the reservoirs are alternately filled and emptied with a fluid circulated between the reservoirs and the processing chambers. Alternately filling and emptying the reservoirs relative to one another at constant rates maintains the fluid level and flow rate in the processing chamber substantially constant.

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